

Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- ◆ 60V,35A, $R_{DS(ON).max}=20m\Omega@V_{GS}=10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

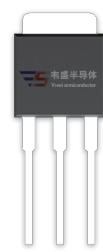
Product Summary

V_{DSS}	60V
$R_{DS(on).max}@V_{GS}=10V$	20m Ω
I_D	35A

Pin Configuration



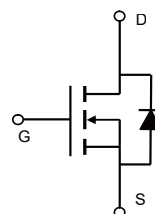
TO-220C



TO-251



TO-252



Schematic

Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V
Continuous drain current ($T_C = 25^{\circ}C$)	I_D	35	A
Continuous drain current ($T_C = 100^{\circ}C$)		22	A
Pulsed drain current ¹⁾	I_{DM}	140	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	39	mJ
Power Dissipation ($T_C = 25^{\circ}C$)	P_D	50	W
Storage Temperature Range	T_{STG}	-55 to +150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to +150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.5	$^{\circ}C/W$

Package Marking and Ordering Information

Device	Device Package	Marking
VSM34N06-TC	TO-220C	VSM34N06-TC
VSM34N06-T2	TO-252	VSM34N06-T2
VSM34N06-T1	TO-251	VSM34N06-T1

Electrical Characteristics

 $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	60	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0	1.6	2.5	V
Drain-source leakage current	I _{DSS}	V _{DS} =60 V, V _{GS} =0 V, T _J = 25°C	---	---	1	μA
		V _{DS} =48 V, V _{GS} =0 V, T _J = 125°C	---	---	10	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V	---	---	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =20 A	---	16	20	mΩ
		V _{GS} =4.5 V, I _D =10 A	---	19	25	mΩ
Forward transconductance	g _{fs}	V _{DS} =5 V , I _D =20A	---	43	---	S
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, F = 1MHz	---	1465	---	pF
Output capacitance	C _{oss}		---	151	---	
Reverse transfer capacitance	C _{rss}		---	103	---	
Turn-on delay time	t _{d(on)}	V _{DD} = 30V,V _{GS} =10V, I _D =20 A	---	11.5	---	ns
Rise time	t _r		---	105	---	
Turn-off delay time	t _{d(off)}		---	127	---	
Fall time	t _f		---	30	---	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.62	---	Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =25 V, I _D =20A, V _{GS} = 10 V	---	6.2	---	nC
Gate to drain charge	Q _{gd}		---	6.1	---	
Gate charge total	Q _g		---	29.5	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _S		---	---	35	A
Pulsed Source Current ⁽³⁾	I _{SM}		---	---	140	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A, T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _S =20A,di/dt=100A/us, T _J =25°C	---	24.8	---	ns
Reverse Recovery Charge	Q _{rr}		---	31.1	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: $V_{DD}=25\text{ V}, V_{GS}=10\text{ V}, L=0.5\text{ mH}, I_{AS}=12.5\text{ A}, R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$.

3: Pulse Test: Pulse Width $\leq 300\mu\text{ s}$, Duty Cycle $\leq 2\%$.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

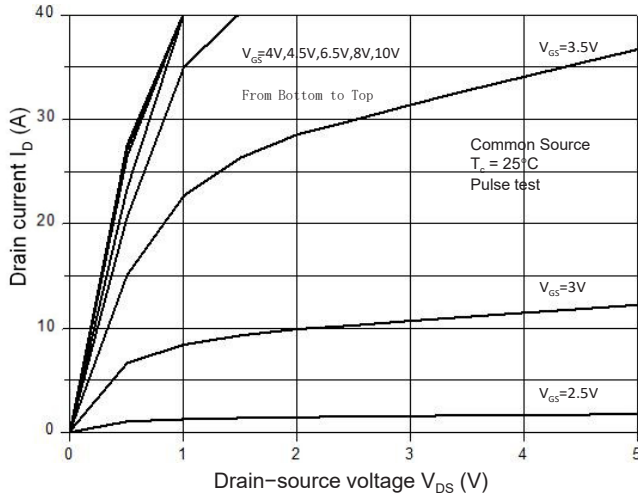


Figure 2. Transfer Characteristics

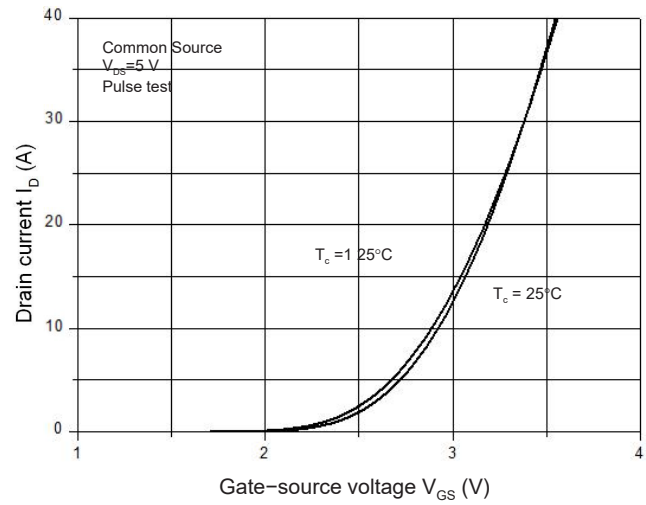


Figure 3. Capacitance Characteristics

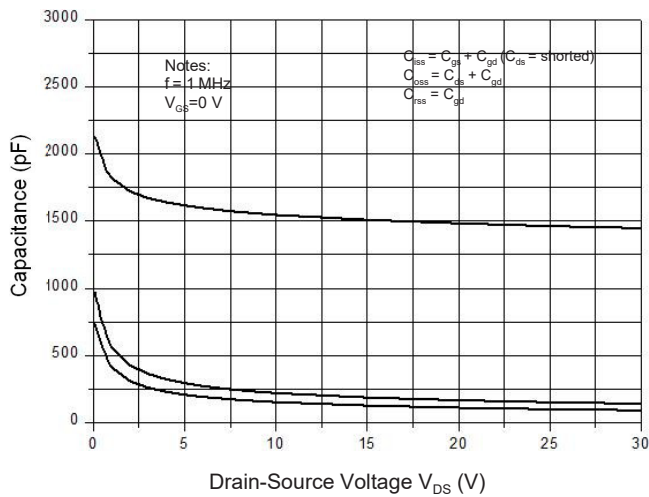


Figure 4. Gate Charge Waveform

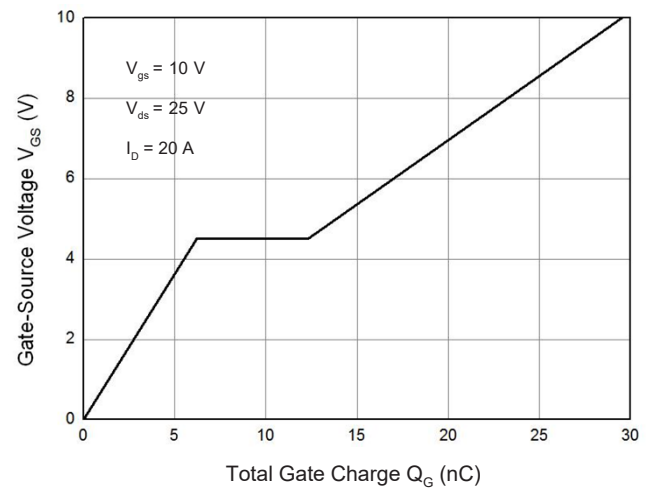


Figure 5. Body-Diode Characteristics

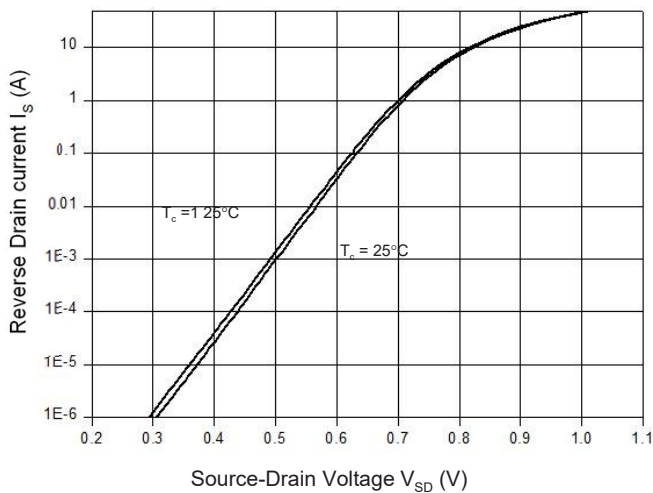


Figure 6. Rdson-Drain Current

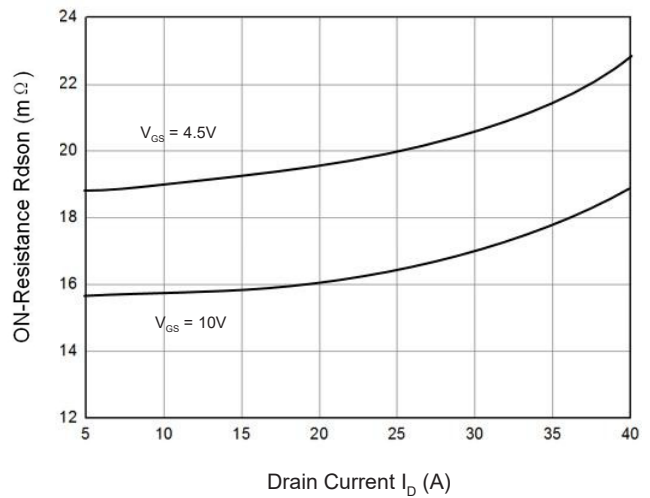


Figure 7. Rdson-Junction Temperature(°C)

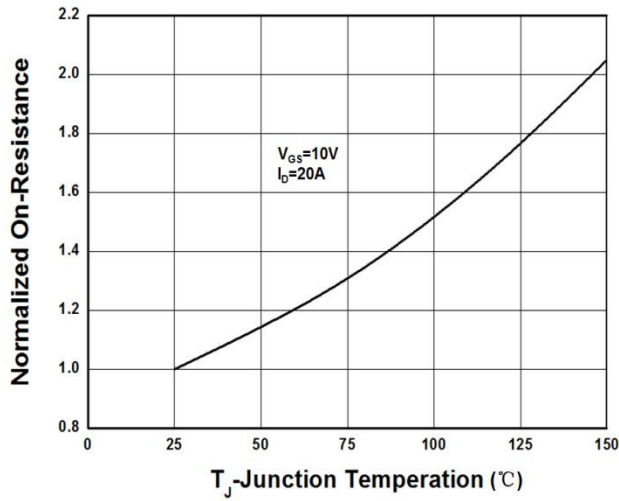


Figure 8. Maximum Safe Operating Area

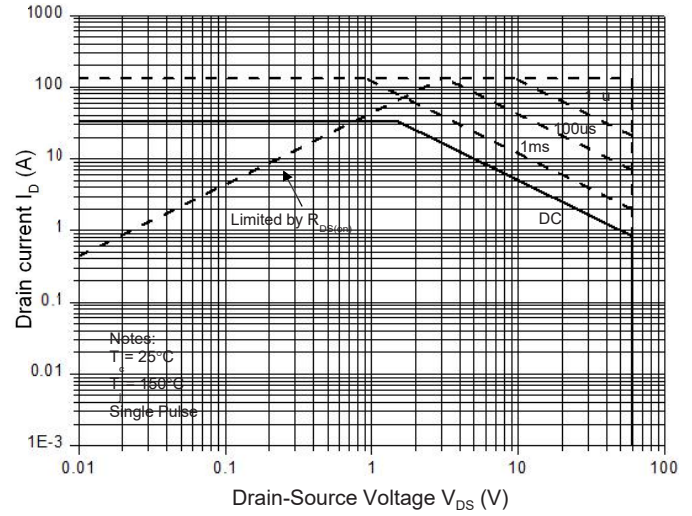
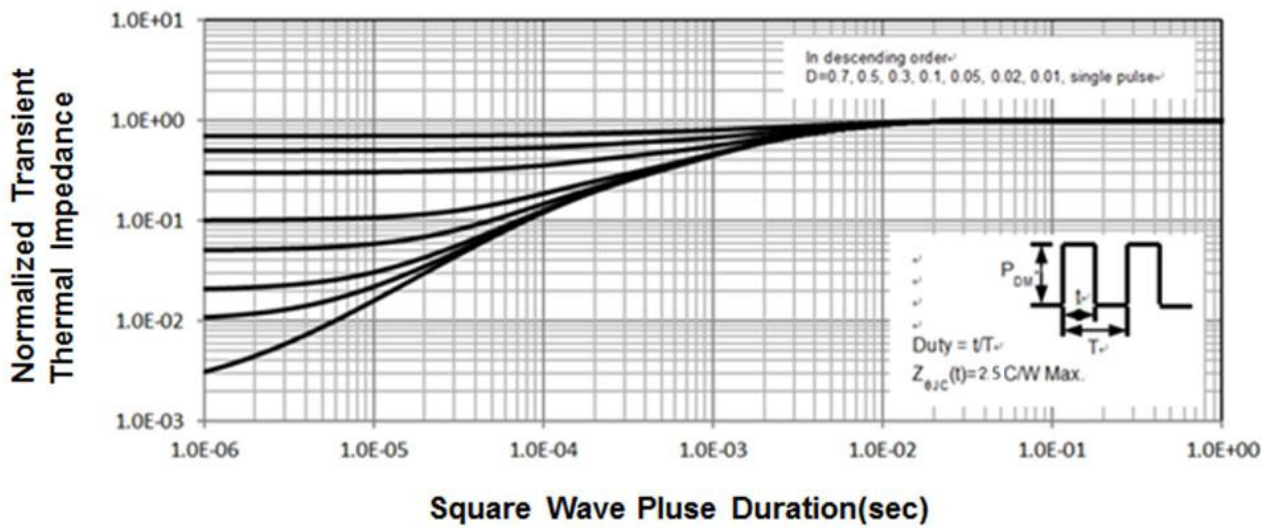


Figure 9. Normalized Maximum Transient Thermal Impedance



Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

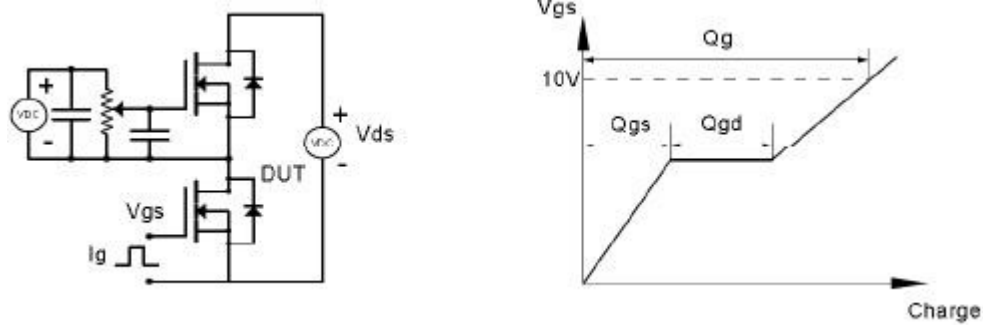


Figure 9. Resistive Switching Test Circuit & Waveforms

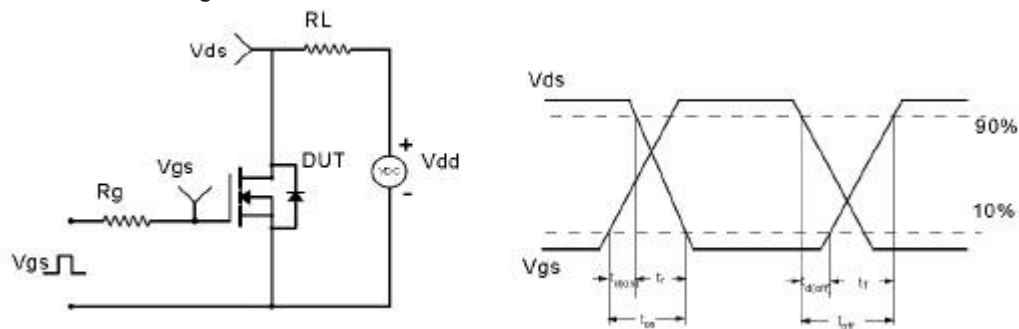


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

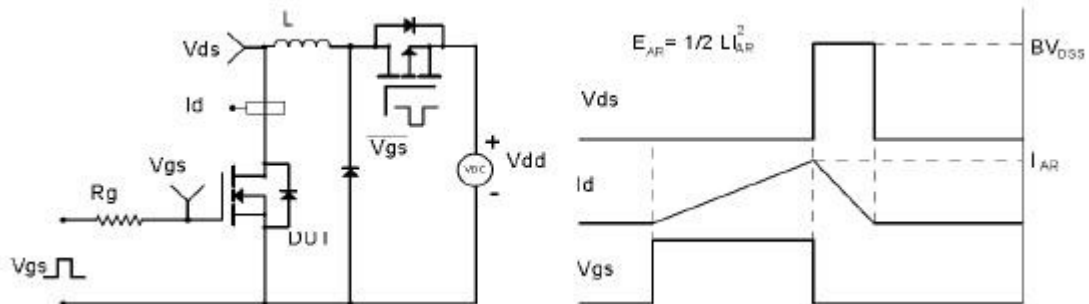


Figure 11. Diode Recovery Circuit & Waveform

